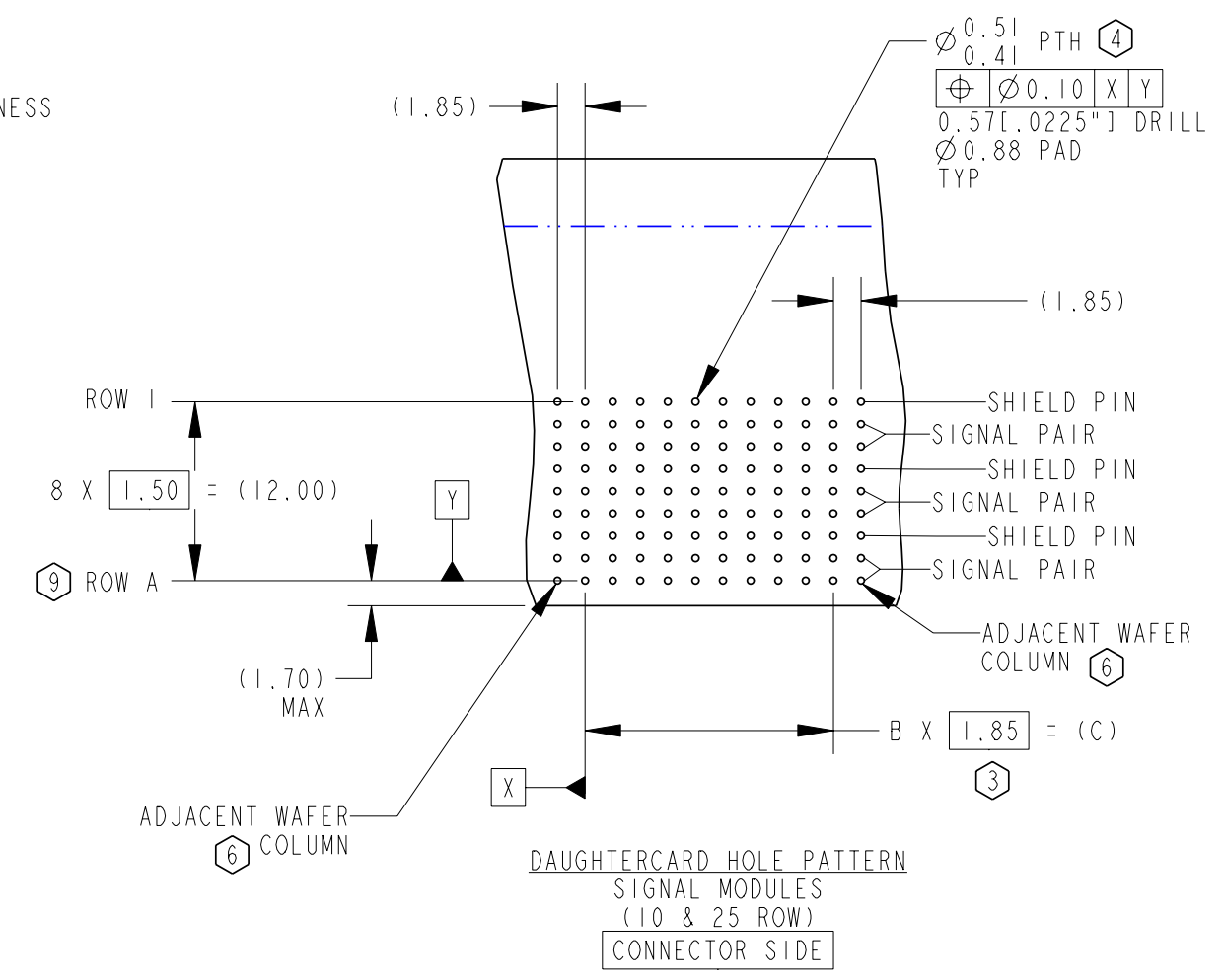
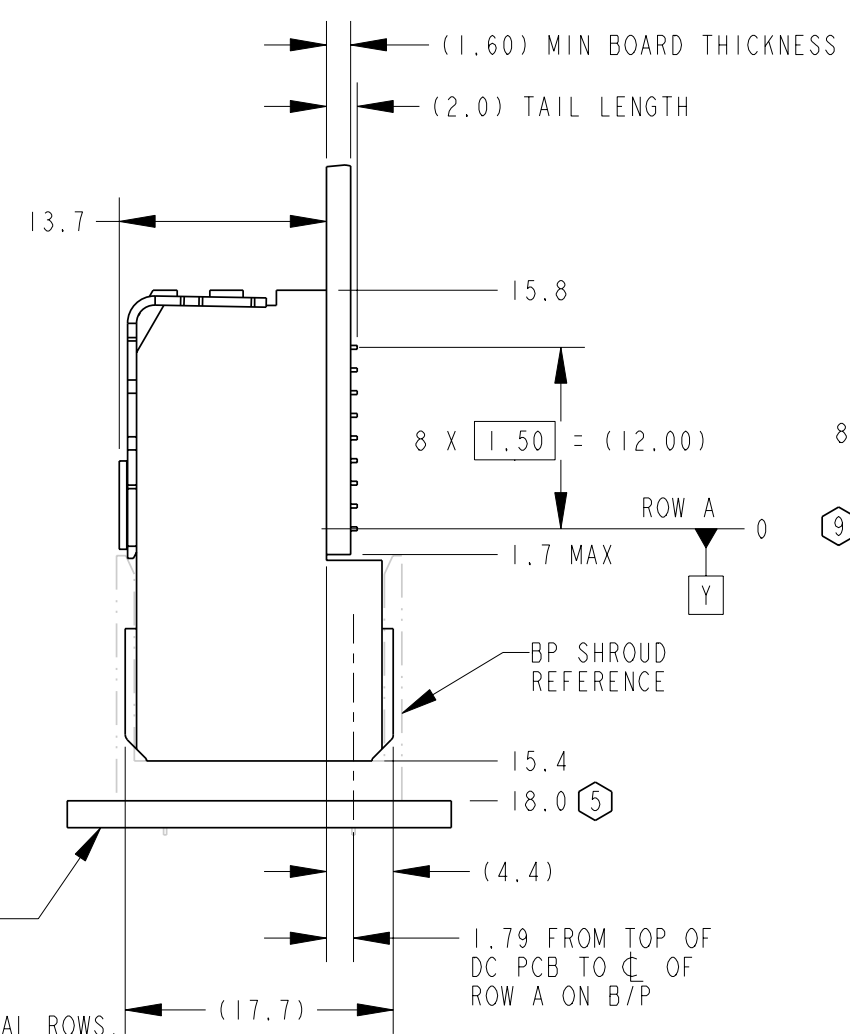
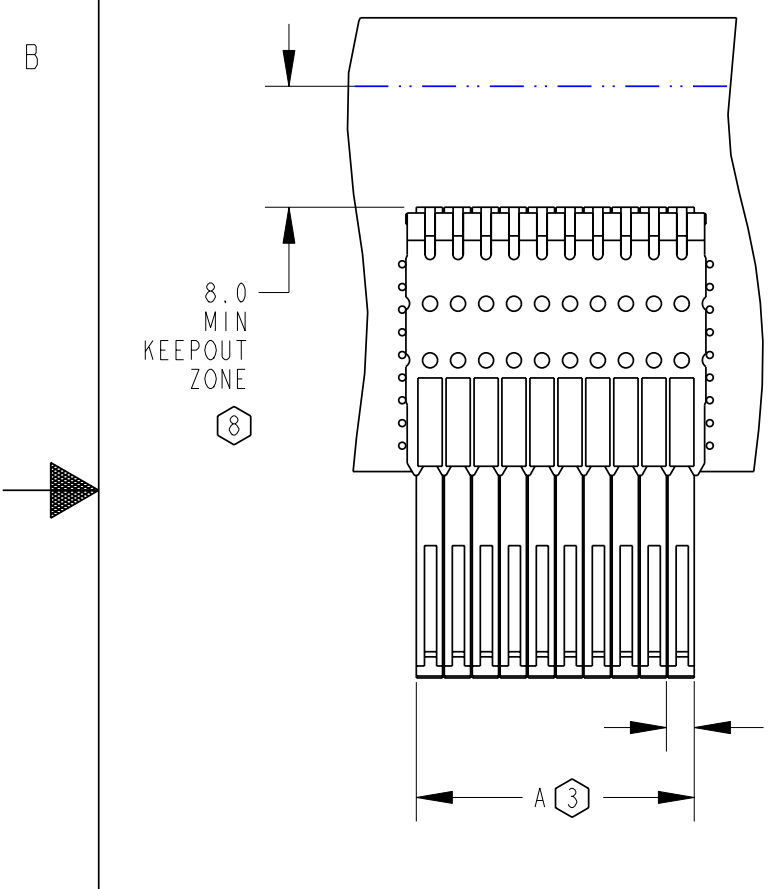


DRW NO. C-165-5101-500 SH 1 REV A

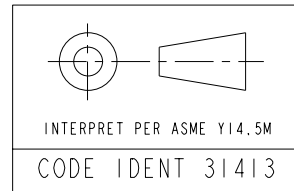
TABLE I		
PART NUMBER	REV	DESCRIPTION
165-5101-735	-	30μ IN. GOLD MATING PLATING

TABLE II			
NUMBER OF WAFERS	A	B	C
10	18.50	9	16.65
25	46.25	24	44.40

ZONE	REV	SCR NO.	DESCRIPTION	BY	DATE	APPROVED
	-	DSMH-6BUQKA.VER01	NEW RELEASE	S.GAGNON	05/11/05	D.SMITH
	A	MLEE-6K9H3D.VER01	CHANGED DRAWING FORMAT	R.CHIFFY	12/13/05	C.SAMMIS



- NOTES:
- ⑨ GROUND ROWS ARE C, F & I. ALL OTHER ROWS ARE SIGNAL ROWS.
  - ⑧ FOR CONNECTOR REPAIRABILITY, USE KEEP OUT ZONE.
  - 7. REFER TO TB-2085 FOR GbX PRODUCT SPECIFICATIONS.
  - ⑥ ADJACENT WAFER COLUMNS SHOWN FOR REFERENCE.
  - ⑤ NOMINAL DIMENSION FOR FULLY SEATED CONNECTOR.
  - ④ STATED PAD SIZE MAY REQUIRE FILLETING. SEE TB-2090 FOR ROUTING GUIDELINES.
  - ③ FOR WAFERS USED IN GROUPS OF 10 OR 25, SEE TABLE II. REFER TO DESIGN GUIDELINES.
  - ② USE 1.85mm NOMINAL FOR DAUGHTERCARD LAYOUT.
  - 1. INTENDED FOR LAYOUT PURPOSES ONLY.



TOLERANCES		DESIGN 02/05/03 R.CHIFFY
0.0	±0.25	DRAWN 9/05/02 R.VASSAR
0.00	±0.13	CHK 02/05/03 J.DUNHAM
0.000	± -	APVD 02/05/03 T.COHEN
ANGLES	± -	

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN MM, DECIMAL MAKER IS PERIOD

**CUSTOMER USE DRAWING**

**Amphenol TCS**  
A Division of Amphenol Corporation  
44 Simon Street, Nashua, NH, 03060 603.879.3000

TITLE: DAUGHTER CARD WAFER ASSEMBLY  
3 PAIR GbX

PART NO. SEE TABLE I  
DRAWING NO. C-165-5101-500  
ProeASSEM P1031-CU-WAFER  
P1031-CU-WAFER .dwg

REV A  
1.7  
1.13

SIZE B SCALE 1.000 SHEET 1 OF 1

DRW NO. C-165-5101-500